LEDA-PNP M76A

Fully-Auto Mapping Sorter

Advantages

1. Cycle time : 130 msec/cycle.
2. Up to 200 grades sorting at once
3. Advanced of DDR Module
   --- Maintenance Free
4. Buffer Station highly enhance transfer Speed
   --- Bin exchange time : 5~10 Sec
5. Simple Mechanical Structure
   --- Loader System designed containing both
      Wafer & Bin Frame effectively eliminates
      maintenance cost.
6. Large effective binning area : up to 80X80 mm
7. Max. 8 inch of double ring handling (option)

Features

1. Short cycle time and high throughput.
2. Auto-theta calibration.
3. A VCM head is employed to achieve ultra-low
   pick & place force (5~200g).
4. Programmable pick & place force control.
5. Advanced defect detection : Crack, Double Dies
   and Pad Inspection.
6. Post-bond inspection
7. Multi languages support.

Applications

1. LED Field
2. Semiconductor Field
3. MEMS
4. Diode / Transistor

The M76A Sorter is an optimized equipment for sorting LED wafer to Bin frame

LED wafer  Bin frame
Specifications

- **Dimension**
  - Wide: 1190mm
  - Height: 1462mm (not included signal-tower)
  - Length: 1390mm
  - Weight: 700Kg

- **Loader**
  - Wafer Cassette:
    - 1 (12 rings for 6” double ring)
    - 1 (8 rings for 8” double ring) \textit{option}
  - Bin Cassette: 7 (25 bins with a single Cassette)

- **Wafer Size**
  - Max 4.6”(117mm) after expansion
  - Max 6”(150mm) after expansion \textit{(option for 8” double Ring)}

- **Bin Area**
  - 80mm X 80mm
  - 58mm X 80mm \textit{(option for 8” double Ring)}

- **Pattern Recognition System**
  - PR System: 256 grey levels
  - Resolution: 640 pixels x 480 pixels
  - PR Accuracy: $\pm$ 0.025 mil \textit{(Die size 64mil x 48mil)}
  - Angle Range: $\pm$ 15°

System Capability

- **System Capability**
  - X-Y Placement: $\pm$ 1.5mil (\(\pm\ 38 \mu m\))
  - Die Rotation: $\pm$ 3°
  - Cycle Time:
    - 130 msec/chip
    - 150 msec/chip \textit{(option for 8” double Ring)}
  - Needle Diameter: 0.7mm(Diameter)- 17mm(Length)

- **Material Handling Capability**
  - Die Size: 6mil x 6mil to 100mil x 100mil

- **Bond Head**
  - Bond Force: 5g to 200g (adjustment)

Facility Requirement

- **Voltage**: 220 VAC
- **Frequency**: 50/60 Hz \textit{(pre-set at factory)}
- **Compressed Air**: 6kg/cm² @ 2 LPM flow rate
- **Power Consumption**: 1.2KW
- **Vacuum**: 0.9kg/cm² @ 1 LPM flow rate